



PATENT APPLICATION

THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q79041

Youichi KUKIMOTO, et al.

Appln. No.: 10/765,931

Confirmation No.: 1863

Group Art Unit: 2823

Filed: January 29, 2004

Examiner: Khiem D. Nguyen

For: SOLDER DISPOSITION METHOD AND SOLDER BUMP FORMING METHOD

AMENDMENT UNDER 37 C.F.R. § 1.114(c)

MAIL STOP RCE

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

This is in response to the Office Action dated February 7, 2006. A Petition and payment for a one-month extension of time are attached, making this Amendment due on or before June 7, 2006. An RCE is being filed concurrently.

Please amend the above-identified application as follows on the accompanying pages.

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